RAIL-TO-RAIL OUTPUT, VERY LOW-NOISE OPERATIONAL AMPLIFIERS

Check for Samples: TL971-Q1, TL972-Q1, TL974-Q1

FEATURES

- **Qualified for Automotive Applications**
- **Rail-to-Rail Output Voltage Swing: ±2.4 V at V_{CC} = ±2.5 V**
- **Very Low Noise Level: 4 nV/√Hz**
- **Ultra-Low Distortion: 0.003%**
- **High Dynamic Features: 12 MHz, 5 V/µs**
- **Operating Range: 2.7 V to 12 V**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B)**
  - **200-V Machine Model (A115-A)**
  - **1500-V Charged-Device Model (C101)**

APPLICATIONS

- **Portable Equipment (CD Players, PDAs)**
- **Portable Communications (Cell Phones, Pagers)**
- **Instrumentation and Sensors**
- **Professional Audio Circuits**

TL971...D PACKAGE (TOP VIEW)

NC – No internal connection

TL972...D OR PW PACKAGE (TOP VIEW)

TL974...PW PACKAGE (TOP VIEW)

DESCRIPTION/ORDERING INFORMATION

The TL97x family of operational amplifiers operates at voltages as low as ±1.35 V and features output rail-to-rail signal swing. The TL97x boast characteristics that make them particularly well suited for portable and battery-supplied equipment. Very low noise and low distortion characteristics make them ideal for audio preamplification.

ORDERING INFORMATION(1)(2)

T_A	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	TL971QDRQ1	TL971Q
	TL972QDRQ1	TL972Q
	TL972QPWRQ1	TL972Q
	TL974QPWRQ1	TL974Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

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ABSOLUTE MAXIMUM RATINGS[1]

over operating free-air temperature range (unless otherwise noted)

V_{CC}	Supply voltage range[2]			2.7 V to 15 V
V_{ID}	Differential input voltage[3]			±1 V
V_{IN}	Input voltage range[4]			V_{CC-} – 0.3 V to V_{CC+} + 0.3 V
θ_{JA}	Package thermal impedance, junction to free air	D package[5]	8 pin	97°C/W
		PW package[5]	8 pin	149°C/W
			14 pin	113°C/W
T_J	Maximum junction temperature			150°C
T_{lead}	Maximum lead temperature	Soldering, 10 seconds		260°C
T_{stg}	Storage temperature range			–65°C to 150°C
ESD	Electrostatic discharge protection	Human-Body Model (HBM)		2000 V
		Machine Model (MM)		200 V
		Charged-Device Model (CDM)		1500 V

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to network ground terminal.
(3) Differential voltages for the noninverting input terminal are with respect to the inverting input terminal.
(4) The input and output voltages must never exceed V_{CC} + 0.3 V.
(5) Package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	12	V
V_{ICM}	Common-mode input voltage	V_{CC-} + 1.15	V_{CC+} – 1.15	V
T_A	Operating free-air temperature	–40	125	°C

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ELECTRICAL CHARACTERISTICS

V_{CC+} = 2.5 V, V_{CC-} = –2.5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A (1)	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage		25°C		1	4	mV
			Full range			6	
αV_{IO}	Input offset voltage drift	V_{ICM} = 0 V, V_O = 0 V	25°C		5		μV/°C
I_{IO}	Input offset current	V_{ICM} = 0 V, V_O = 0 V	25°C		10	150	nA
I_{IB}	Input bias current	V_{ICM} = 0 V, V_O = 0 V	25°C		200	750	nA
			Full range			1000	
V_{ICM}	Common-mode input voltage		25°C	–1.35		1.35	V
CMRR	Common-mode rejection ratio	V_{ICM} = ±1.35 V	25°C	60	85		dB
SVR	Supply-voltage rejection ratio	V_{CC} = ±2 V to ±3 V	25°C	60	70		dB
A_{VD}	Large-signal voltage gain	R_L = 2 kΩ	25°C	70	80		dB
V_{OH}	High-level output voltage	R_L = 2 kΩ	25°C	2	2.4		V
V_{OL}	Low-level output voltage	R_L = 2 kΩ	25°C		–2.4	–2	V
I_{source}	Output source current		25°C	1.2	1.4		mA
		V_{OUT} shorted to –2.5 V	Full range	1			
I_{sink}	Output sink current		25°C	50	80		mA
		V_{OUT} shorted to +2.5 V	Full range	25			
I_{CC}	Supply current (per amplifier)	Unity gain, No load	25°C		2	2.8	mA
			Full range			3.2	
GBWP	Gain bandwidth product	f = 100 kHz, R_L = 2 kΩ, C_L = 100 pF	25°C	8.5	12		MHz
SR	Slew rate	A_V = 1, V_{IN} = ±1 V	25°C	3.5	5		V/μs
			Full range	3			
Φm	Phase margin at unity gain	R_L = 2 kΩ, C_L =100 pF	25°C		60		°
Gm	Gain margin	R_L = 2 kΩ, C_L =100 pF	25°C		10		dB
V_n	Equivalent input noise voltage	f = 100 kHz	25°C		4		nV/√Hz
THD	Total harmonic distortion	f = 1 kHz, A_v = –1, R_L = 10 kΩ	25°C		0.003		%

(1) Full range T_A = –40°C to 125°C

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TYPICAL CHARACTERISTICS

GAIN AND PHASE vs FREQUENCY

GAIN AND PHASE vs FREQUENCY

TOTAL HARMONIC DISTORTION vs FREQUENCY

TOTAL HARMONIC DISTORTION + NOISE vs OUTPUT VOLTAGE

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TYPICAL CHARACTERISTICS (continued)

TOTAL HARMONIC DISTORTION + NOISE vs OUTPUT VOLTAGE

INPUT VOLTAGE NOISE vs FREQUENCY

GAIN BANDWIDTH PRODUCT vs OUTPUT CURRENT

GAIN BANDWIDTH PRODUCT vs SUPPLY VOLTAGE

TYPICAL CHARACTERISTICS (continued)

PHASE MARGIN vs OUTPUT CURRENT

PHASE MARGIN vs SUPPLY VOLTAGE

GAIN MARGIN vs SUPPLY VOLTAGE

INPUT RESPONSE

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TYPICAL CHARACTERISTICS (continued)

POWER-SUPPLY RIPPLE REJECTION vs FREQUENCY

OUTPUT VOLTAGE vs OUTPUT CURRENT

OUTPUT IMPEDANCE vs FREQUENCY

SLEW RATE vs SUPPLY VOLTAGE

REVISION HISTORY

Changes from Original (March 2009) to Revision A **Page**

- Removed packaging column from the ordering information table. 1
- Changed V_{OUT} = ±2.5 V to V_{OUT} shorted to -2.5 V for I_{source}, and changed V_{OUT} = ±2.5 V to V_{OUT} shorted to +2.5 V for I_{sink}. 3

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL971QDRQ1	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL971Q
TL971QDRQ1.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL971Q
TL972QDRQ1	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL972Q
TL972QDRQ1.A	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL972Q
TL972QPWRQ1	Active	Production	TSSOP (PW) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL972Q
TL972QPWRQ1.A	Active	Production	TSSOP (PW) | 8	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL972Q
TL974QPWRQ1	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL974Q
TL974QPWRQ1.A	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TL974Q

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TL971-Q1, TL972-Q1, TL974-Q1 :

- Catalog : TL971, TL972, TL974

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL972QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL972QPWRQ1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL974QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL974QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL972QDRQ1	SOIC	D	8	2500	353.0	353.0	32.0
TL972QPWRQ1	TSSOP	PW	8	2000	353.0	353.0	32.0
TL974QPWRQ1	TSSOP	PW	14	2000	353.0	353.0	32.0
TL974QPWRQ1	TSSOP	PW	14	2000	353.0	353.0	32.0

PACKAGE OUTLINE

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0014A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

NON-SOLDER MASK DEFINED (PREFERRED)

SOLDER MASK DEFINED

SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

LAND PATTERN EXAMPLE
SCALE:10X

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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